

ABSTRACT**LAND GRID ARRAY (LGA) INTERPOSER WITH ADHESIVE-RETAINED CONTACTS
AND METHOD OF MANUFACTURE**

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A novel Land Grid Array (LGA) interposer with adhesive-retained contacts and method of manufacture provide improved reliability in LGA mounting applications. A flexible adhesive is used to secure LGA interposer contacts to the walls of voids
10 through an interposer frame. The contacts may be spring contacts or "fuzz button" type contacts. The use of a flexible adhesive provides for floating movement of the contacts within the voids so that thermal expansion stresses do not cause unbalanced compression of the contacts that could otherwise occur with a
15 fixed attachment of the contacts to the frame. The resulting interposer can provide reliable electrical connection from LGA lands on an integrated circuit package to lands on an electronic assembly that is highly tolerant of thermal expansion differences, while eliminating migration of the contacts out of
20 the voids that could otherwise cause shorting or disconnection.